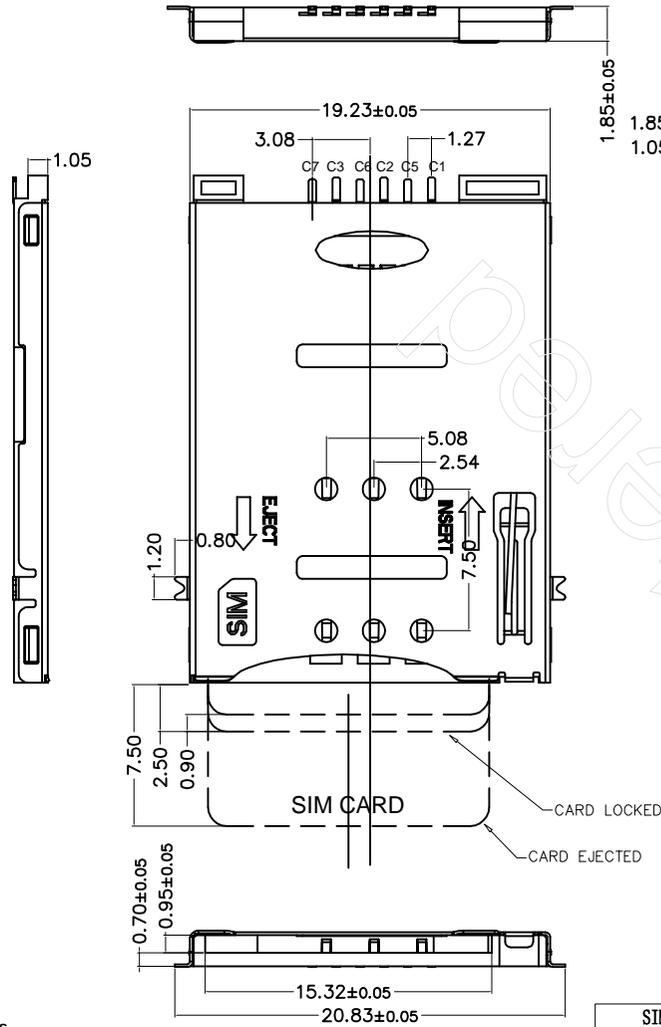
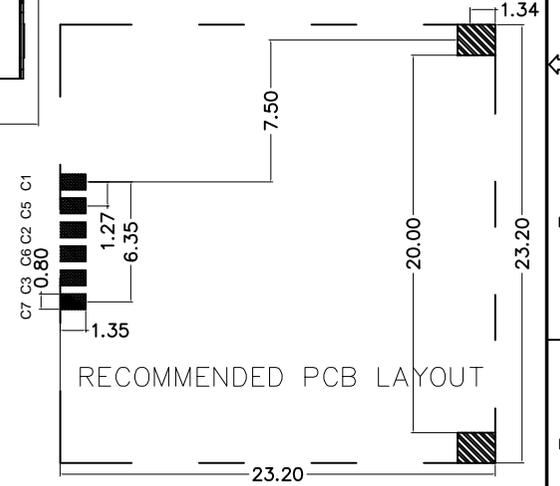
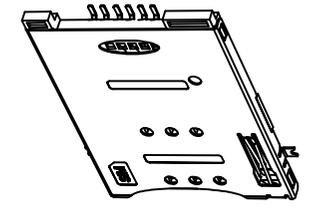
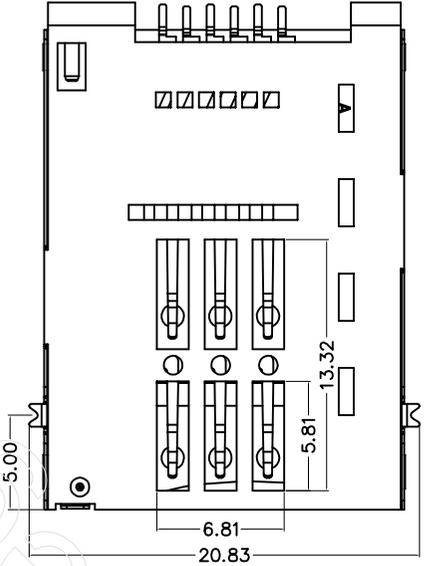


* 所有原料材质, 生产制程, 电镀必须符合ROHS要求

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ALL SOLDER TAILS AND LATCH



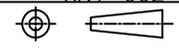
- 1.SPECIFICATIONS
INSULATION RESISTANCE: 500M min.AT DC 500V DC
WITHSTANDING VOLTAGE: 250V ACrms FOR 1 MINUTE
CONTACT RESISTANCE: 100M max. AT 10MA/20mV max
CURRENT RATING: 0.5A
VOLTAGE RATING: 5.0 vrms
OPERATING TEMP.RANGE:-55 C+85 C
MATING CYCLES: 5000 INSERTIONS
- 2.MATERIAL:
INSULATOR: H-TEMPERATURE PLASTIC,UL 94V--0,
COLOR*BLACK
TERMINAL: COPPER ALLOY,T=0.15mm
SHELL: STAINLESS STEEL,T=0.15mm
- 3.FINISH:
TERMINAL:50u" min NICKEL UNDERPLATED ON ALLOVER,GOLD PLATING
ON CONTACT ARER, 80u"min TIN ON SOLDER TAIL.
SHELL:50u" NICKEL UNDERPLATED ON ALLOVER, GOLD FLASH ON SOLDER LATCH

SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



深圳市鑫南天科技有限公司

Shen zhen Shi Xin Nan Tian Industrial Co., Ltd

DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.25 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 1°	PRODUCT NAME : SIM PUSH 6P SMT	DRAWING: COCO	DATE: 2012/5/10
	PRODUCT NO. : 0081BAAS06A	CHECK: JANY	DATE: 2012/5/10
XNT-002 	DRAWING NO. :	APPROVED: JEFF	DATE: 2012/5/10
	SCALE: 1:1	DWG ID: P D	REV.: A

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				



SIM CARD(PUSH/PUSH) PRODUCT SPECIFICATION

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1.SCOPE

This specification covers performance , tests and quality requirements for SIM CARD(PUSH/PUSH) CONNECTORS.

2.MATERIAL AND FINISH

Insulator : LCP ,COLOR:BLACK, rated UL94V-0

Contact: (A) Material Phosphor Bronze , T=0.15mm (B) Finish:Selective Gold Plated on Contact Area, Plated Tin 120u” on Solder Area

Shell: (A) Material:SUS304-1/2H.T=0.15mm

(B) Finish: 50u” NICKEL Plated on allover, gold flash on solder ground.

3.RATINGS

Voltage Rating : 250V AC

Current Rating : 0.5Amps Max

Contact Resistance (signal) : 100mΩ Initial (140mΩ After Test) Max.

Insulation Resistance : 500mΩ Min. at 500VDC .

Dielectric Withstanding Voltage : 250VAC/Minute .

Operating Temperature : -55°C~+85°C

Mating Cycle : 5000 Insertions

4.PERFORMANCE

4.1ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Low Level Contact Resistance	Mate dummy card, measure by dry circuit, 20mV max,10Ma max. (EIA 364-23)	100 mΩ Max. Initial 100+/-40mΩMax.Final
2	Insulation Resistance	Apply a 500V DC between adjacent Terminals and between terminals to ground (EIA364-21)	500MΩ Min
3	Dielectric Withstanding Voltage	Apply a voltage 500V AC for 1 minute between adjacents Terminals and between terminals to ground (EIA364-20)	
4	Card Detect	{ OPEN MODE} Mate dummy card ,measure of contact resistance { CLOSE MODE} Unmate dummy card, measure of contact resistance	500MΩ Min 50 mΩ Max

4.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Insertion and Withdrawal	Insert and withdraw memory card at a rate of 25±3 mm per	Push force: 1kgf Max Pull force: 0.1kgf Min



**SIM CARD(PUSH/PUSH)
PRODUCT SPECIFICATION**

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	force	minute. (EIA 364-13)	
2	Durability	Insertion and extraction are repeated 5000 cycles with the actually card at the speed rate of 400~600 cycles/hour. Exchange the actually card every 2000 cycles (EIA364-09)	Appearance:No damage contact Resistance:100mΩ Max.Measuring by dummy card
3	Normal force	Push the contact point. Measure the normal force at the deformend direction	25g/PIN Min
4	Vibration	Mate dummy card and subject to the following vibration conditions, for aperiod of 2 hours in each of 3 mutually perpendicular axis, passing DC 1mA during the test. Amplitude:1.5mm P-P or 49m/s ² Frequency:10-55-10 Hz Shall be traversed in 20 minute. (EIA 364-28 Condition 1)	Appearance:No damage. Contact resistance:100mΩ Discontinuity:100 Nanosecond max
5	Shork (Mechanical)	Mate a dummy card and subject to the follwing shork conditions. 3 shorks shall be applied along 3 mutually perpendicular axis passing DC 1Ma current during the test.(EIA-364-27B)	Appearance:No damage. Contact resistance:100mΩ Discontinuity:0.1Microsecond max

4.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Humidity (steady state)	Mate a DUMMY CARD AND EXPOSE TO 60±2°C for 96 hours Relative humidity 90.Upon completion of the exposure period,the test specimens shall be conditioned at anibient room conditions for 1 to 2	No appearance damaged contact resistance:100 mΩ Max. Meet Dielectric strength Test. Insulation resistance:100 MΩ Min



**SIM CARD(PUSH/PUSH)
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		measurements shall be performed (EIA-364-31A)	
2	Temperature cycling	Mate,un-unmate dummy card 200 cycles. Then. a)-55±3°C for 30 minute b)85±2°C for 30 minuter Repeat a) b) 1cycles Then put in ambient room 1~2hour. Transit time in 3 minute(EIA 364-32)	No appearance damaged contact resistance:100 mΩ Max.
3	Heat Resistance	Mate a dummy card and expose to 70±2°C for 48Hr Upon completion of the exposure period,the test specimens shall be conditioned at ambient room conditions for 1 to 2Hr,after which the specified measurements shall be performed. (MIL-STD-202 Method 108)	No appearance damaged contact resistance:100 mΩ Max.
4	Cold Resistance	Mate a dummy card and expose to -52°C for 96Hr.. Upon completion of the exposure period,thetest specimens shall be conditioned at ambient room conditions for 1to 2Hr,after which the specified measurements shall be performed. (mil-std-202)	No appearance damaged contact resistance:100 mΩ Max.
5	Salt spray	Mate dummy card and exposed to the follwing salt mist conditions. Upon completion of the exposure period,salt deposits shall be removed by a gentle wash or dip in running water,after which the specified measurements shall be performed. NaCL solution Ambient temperature 35±2°C Concentration 5% Spray time: 8Hrs Gentle wash after test (EIA-364-26)	No appearance damaged contact resistance:100 mΩ Max.
6	Resistance to	Touch the terminal with the soldering	No appearance damaged

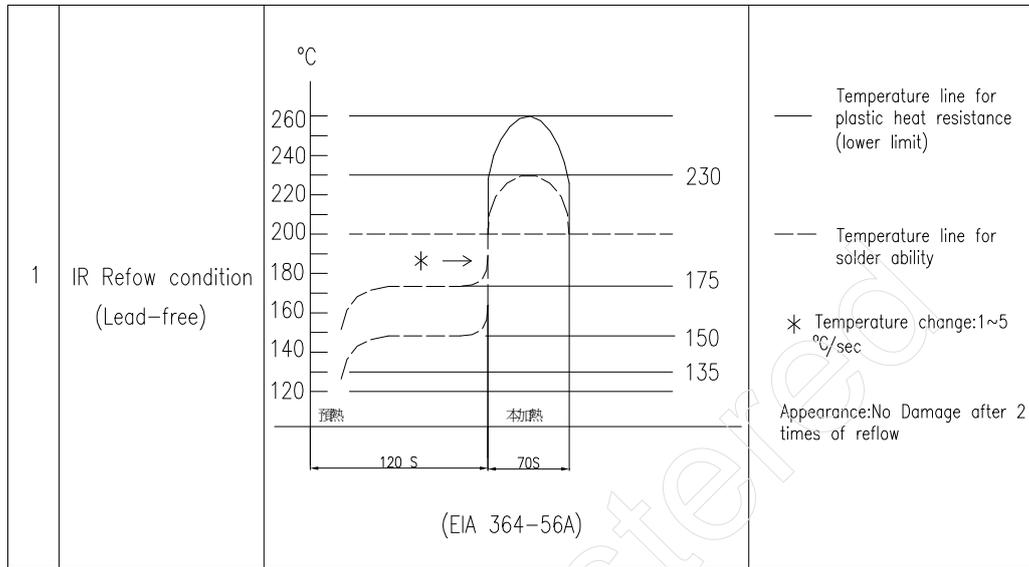


SIM CARD(PUSH/PUSH) PRODUCT SPECIFICATION

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		form the tip of tail for 3±0.5sec	
7	Solder ability	245±5°C (EIA-364-52)	Solder coverage: 95%Min

4.4 INFRARED REFLOW CONDITIONS



5. TEST SEQUENCE DIAGRAM

Test Description	Test Group						
	1	2	3	4	5	6	7
Examination product	1, 6	1, 7	1, 5	1, 5	1, 5	1, 5	1, 3
Low Level Contact Resistance	2, 5		2, 4	2, 4	2, 4	2, 4	
Insulation Resistance		2, 5					
Withstanding Voltage		6					
Durability	3						
Vibration						3	
Shock	4						
Humidity Resistance		4					
Temperature cycling		3					
Heat Resistance					3		
Salt Spray			3				
Cold Resistance				3			
Insertion and Withdrawal force							2
Test Description	Supplemental test						
Terminal Normal force	5PCS,						
Resistance to solder heat	5PCS						
Solderability	5 PCS						